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Middle Power LED Series 2835 0.5W 9V Ra80 Hot bin

LM283BS+



Designed for better Im/\$ (Lamps)





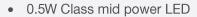










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1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +85	°C	-
Storage Temperature	T_{stg}	-40 ~ +85	°C	-
LED Junction Temperature	Tj	115	°C	-
Forward Current	l _F	70	mA	-
Peak Pulsed Forward Current	l _{Ep}	140	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	2	kV	-

Note:

Proper current derating must be observed to maintain junction temperature below the maximum at all time.



b) Electro-optical Characteristics (I_F = 60 mA, T_s = 25 °C)

ltem	Unit	Rank	Bin	Min.	Тур.	Max.
			GZ	8.8	-	9.1
5 114 11 147	.,	SG	G1	9.1	_	9.4
Forward Voltage (VF)	V	or SK	G2	9.4	_	9.7
			G3	9.7		10.0
Color Rendering Index (Ra)	-	5		80	_	-
Thermal Resistance (junction to solder point)	°C/W			-	15	-
Beam Angle	o			-	120	-

Note:

Samsung maintains measurement tolerance of: forward voltage = ± 0.1 V, CRI = ± 3



b) Electro-optical Characteristics (I_F = 60 mA, T_s = 25 °C)

ltem	CRI (R _a)	Nominal	Bin	60mA										
item	Min.	Min. CCT (K)		Min.	Max.									
		2700	S1	59.0	64.0									
		3000	S1	61.0	66.0									
	80										3500	S1	62.5	67.5
Luminous Flux (Φ_v)		4000	S1	64.5	69.5									
		5000	S1	66.0	71.0									
	5700 6500	5700	S1	65.0	70.0									
		6500	S1	64.5	69.5									

Note:

Samsung maintains measurement tolerance of: forward voltage = ± 0.1 V, luminous flux = ± 5 %, CRI = ± 3



2. Product Code Information

1	2	3						9						15	16	17	18
S	Р	М	W	н	2	2	2	9	6	Q	5	S	G	R	0	S	1

Digit	PKG Information	Code	Specification					
1 2 3	Samsung Package Middle Power	SPM	Middle po	Middle power				
4 5	Color	WH	White					
6	Product Version	2	1st versio	n				
7 8 9	Form Factor	229	2.8 x 3.5 x	c 0.65 mm	ı; 2 pads; 1chip;			
10	Sorting Current (mA)	6	60 mA					
11	Chromaticity Coordinates	Q	Hot temp					
12	CRI	5	Min. 80					
13 14	Forward Voltage (V)	SG	8.8~10.0	Bin Code	GZ 8.8 ~ 9.1 G1 9.1 ~ 9.4 G2 9.4 ~ 9.7 G3 9.7 ~ 10.0			
15 16	CCT (K)	 W☆ V☆ U☆ T☆ R☆ Q☆ P☆ 	2700 3000 3500 4000 5000 5700 6500 ☆: "0'	Bin Code:	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG R1, R2, R3, R4, R5, R6, R7, R8, R9,RA,RB,RC,RD,RE,RF,RG Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9,QA,QB,QC,QD,QE,QF,QG P1, P2, P3, P4, P5, P6, P7, P8, P9,PA,PB,PC,PD,PE,PF,PG bin) "M" (Quarter bin) or "K" (kitting bin)			
17 18	Luminous Flux	S1	Bin S1 Code					



a) Luminous Flux Bins ($I_F = 60$ mA, $T_s = 25$ °C)

CRI (R₃) Min.	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Φ _v , lm)
	2700	SPMWH22296Q5SGW☆S1	S1	59.0 ~ 64.0
	3000	SPMWH22296Q5SGV☆S1	S1	61.0 ~ 66.0
	3500	SPMWH22296Q5SGU☆S1	S1	62.5 ~ 67.5
80	4000	SPMWH22296Q5SGT☆S1	S1	64.5 ~ 69.5
	5000	SPMWH22296Q5SGR☆S1	S1	66.0 ~ 71.0
	5700	SPMWH22296Q5SGQ☆S1	S1	65.0 ~ 70.0
	6500	SPMWH22296Q5SGP☆S1	S1	64.5 ~ 69.5

Note:



b) Kitting rule

1) Kitting bin Concept

- 1. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
- 2. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (GZ+GZ), (G1+G1), (G2+G2) or (G3+G3).
- 3. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

[Kitting example]

D	E	F	G
9	A	В	O
5	6	7	8
1	2	3	4

[Binning Information]

	Bin #1	Bin #2
	GZ	GZ
VF	G1	G1
VF	G2	G2
	G3	G3
	1, 2, 5 bin	C, F, G bin
CIE	6, 7, A, B bin	6, 7, A, B bin
	3, 4, 8 bin	9, D, E bin



c) Color Bins (I_F = 60 mA, T_s = 25 °C)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins
		SPMWH22296Q5SGW0S1	W0 (Whole bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
	2700	SPMWH22296Q5SGWMS1	WM (Quarter bin)	W6, W7, WA, WB
		SPMWH22296Q5SGWKS1	WK (Kitting bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
		SPMWH22296Q5SGV0S1	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
	3000	SPMWH22296Q5SGVMS1	VM (Quarter bin)	V6, V7, VA, VB
		SPMWH22296Q5SGVKS1	VK (Kitting bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
		SPMWH2296Q5SGU0S1	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
	3500	SPMWH22296Q5SGUMS1	UM (Quarter bin)	U6, U7, UA, UB
		SPMWH22296Q5SGUKS1	UK (Kitting bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
		SPMWH22296Q5SGT0S1	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
80	4000	SPMWH22296Q5SGTMS1	TM (Quarter bin)	T6, T7, TA, TB
		SPMWH22296Q5SGTKS1	TK (Kitting bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
		SPMWH22296Q5SGR0S1	R0 (Whole bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9 RA,RB,RC,RD,RE,RF,RG
	5000	SPMWH22296Q5SGRMS1	RM (Quarter bin)	R6, R7, RA, RB
		SPMWH22296Q5SGRKS1	RK (Kitting bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9 RA,RB,RC,RD,RE,RF,RG
		SPMWH22296Q5SGQ0S1	Q0 (Whole bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9 QA,QB,QC,QD,QE,QF,QG
	5700	SPMWH22296Q5SGQMS1	QM (Quarter bin)	Q6, Q7, QA, QB
		SPMWH22296Q5SGQKS1	QK (Kitting bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9 QA,QB,QC,QD,QE,QF,QG
		SPMWH22296Q5SGP0S1	P0 (Whole bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9 PA,PB,PC,PD,PE,PF,PG
	6500	SPMWH22296Q5SGPMS1	PM (Quarter bin)	P6, P7, PA, PB
		SPMWH22296Q5SGPKS1	PK (Kitting bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9 PA,PB,PC,PD,PE,PF,PG

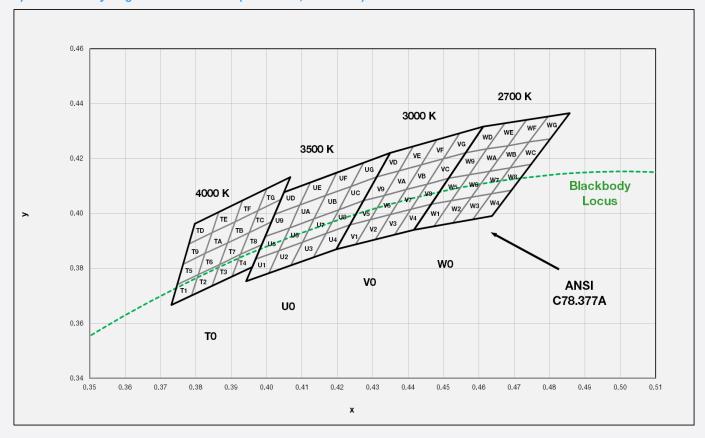


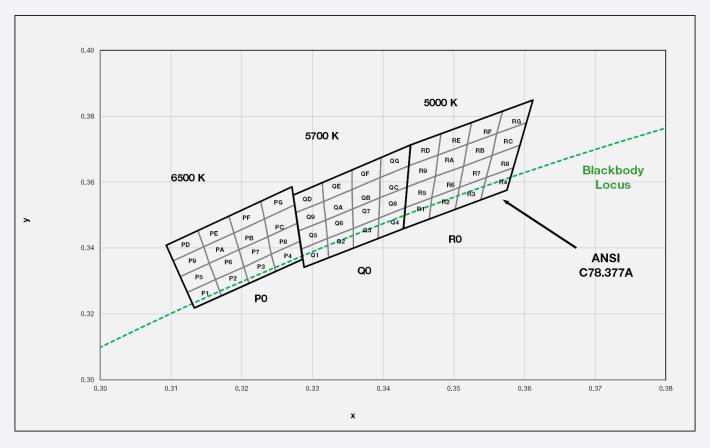
d) Voltage Bins (I_F = 60 mA, T_s = 25 °C)

CRI (R₃) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
				GZ	8.8 ~ 9.1
			SG	G1	9.1 ~ 9.4
-	-	-	or ···	G2	9.4 ~ 9.7
			•••	G3	9.7 ~ 10.0



e) Chromaticity Region & Coordinates (I_F = 60 mA, T_s = 25 °C)







Region	CIE x	CIE y	Region	CIE x	CIE y
		W rank	(2700 K)		:
	0.4417	0.3940		0.4515	0.4128
10/4	0.4472	0.3953	14/0	0.4573	0.4141
W1	0.4522	0.4047	W9	0.4623	0.4235
	0.4466	0.4034		0.4563	0.4222
	0.4472	0.3953		0.4573	0.4141
	0.4527 0.3966		0.4631	0.4153	
W2	0.4579	0.4059	WA	0.4683	0.4247
	0.4522	0.4047		0.4623	0.4235
	0.4527	0.3966		0.4631	0.4153
	0.4582	0.3978		0.4689	0.4166
W3	0.4635	0.4072	WB	0.4742	0.4260
	0.4579	0.4059		0.4683	0.4247
	0.4582	0.3978		0.4689	0.4166
	0.4637	0.3991	WC	0.4747	0.4179
W4	0.4692	0.4085		0.4802	0.4272
	0.4635	0.4072		0.4742	0.4260
	0.4466	0.4034		0.4563	0.4222
	0.4522	0.4047		0.4623	0.4235
W5	0.4573	0.4141	WD	0.4673	0.4329
	0.4515	0.4128		0.4612	0.4316
	0.4522	0.4047		0.4623	0.4235
	0.4579	0.4059		0.4683	0.4247
W6	0.4631	0.4153	WE	0.4735	0.4341
	0.4573	0.4141		0.4673	0.4329
	0.4579	0.4059		0.4683	0.4247
	0.4635	0.4072		0.4742	0.4260
W7	0.4689	0.4166	WF	0.4796	0.4354
	0.4631	0.4153		0.4735	0.4341
	0.4635	0.4072		0.4742	0.4260
	0.4692	0.4085		0.4802	0.4272
W8	0.4747	0.4179	WG	0.4857	0.4366
	0.4689	0.4166		0.4796	0.4354

Region	CIE x	CIE y	Region	CIE x	CIE y
V rank (3000 K)					
	0.4197	0.3870		0.4273	0.4046
V1	0.4252	0.3888	V0	0.4333	0.4066
VI	0.4293	0.3977	V9	0.4374	0.4155
	0.4235	0.3958	88	0.4311	0.4133
	0.4252	0.3888		0.4333	0.4066
V2	0.4307	0.3905	\/^	0.4394	0.4087
VZ	0.4350	0.3996	VA	0.4437	0.4178
	0.4293	0.3977		0.4374	0.4155
	0.4307	0.3905		0.4394	0.4087
VO	0.4362	0.3923	VD	0.4454	0.4107
V3	0.4408	0.4015	VB	0.4500	0.4200
	0.4350	0.3996		0.4437	0.4178
	0.4362	0.3923		0.4454	0.4107
V4	0.4417	0.3940	VO	0.4515	0.4128
V4	0.4466	0.4034	940 VC 0.4515 0.4563 015 0.4500 958 0.4311	0.4563	0.4222
	0.4408	0.4015		0.4200	
	0.4235	0.3958		0.4311	0.4133
VE	0.4293	0.3977	VD	0.4374	0.4155
V5	0.4333	0.4066	VD	0.4415	0.4245
	0.4273	0.4046		VA 0.4311 VA 0.4333 0.4394 0.4374 0.4374 0.4394 0.4454 0.4500 0.4453 0.4563 0.4500 0.4311 0.4374 0.4374 0.4374 VE 0.4415 0.4437 VE 0.4481 0.4415 0.4500 VF 0.4563 0.4500 VG 0.4563 0.4500 VG 0.4563	0.4221
	0.4293	0.3977	VD	0.4374	0.4155
Ve	0.4350	0.3996	VE	0.4374 0.4415 0.4349 0.4374 0.4437	0.4178
V6	0.4394	0.4087	VE	0.4481	0.4269
	0.4333	0.4066		0.4415	0.4245
	0.4350	0.3996		0.4437	0.4178
\/7	0.4408	0.4015	\/_	0.4500	0.4200
V7	0.4454	0.4107	VF	0.4546	0.4292
	0.4394 0.4087	0.4481	0.4269		
	0.4408	0.4015		0.4500	0.4200
\/O	0.4466	0.4034	VO	0.4563	0.4222
V8	0.4515	0.4128	VG	0.4612	0.4316
	0.4454	0.4107		0.4546	0.4292



Region	CIEx	CIE y	Region	CIE x	CIE y
	:	U rank	(3500 K)		
	0.3942	0.3753		0.3995	0.3916
114	0.4006	0.3782	110	0.4065	0.3948
U1	0.4035	0.3865	09	0.4094	0.4031
	0.3969	0.3834		0.4065 0.4094 0.4022 0.4065 0.4134 0.4167 0.4094 0.4134 0.4204 0.4239 0.4167 0.4204 0.4273 0.4311 0.4239 0.4022 0.4094 0.4124 0.4049 0.4167 0.4199 0.4124 0.4167 0.4239 0.4274 0.4199 0.4239 0.4311 0.4349	0.3997
	0.4006	0.3782		0.4065	0.3948
110	0.4069	0.3812		0.4134	0.3981
U2	0.4102	0.3896	UA	0.4167	0.4065
	0.4035	0.3865	0.3995 0.4065 0.4094 0.4022 0.4065 0.4065 0.4094 0.4167 0.65 0.4094 0.4167 0.4204 0.4239 0.66 0.4167 0.4239 0.4239 0.4022 0.40311 0.4239 0.40311 0.4239 0.40404 0.4124 0.4049 0.4124 0.4049 0.4124 0.4049 0.4124 0.4049 0.4124 0.4094 0.4124 0.4094 0.4124 0.4049 0.4124 0.4094 0.4167 0.4199	0.4031	
	0.4069	0.3812		0.4134	0.3981
110	0.4133	0.3841	HP	0.4204	0.4013
U3	0.4168	0.3927	UB	0.4239	0.4099
	0.4102	0.3896	***	0.4167	0.4065
	0.4133	0.3841		0.4204	0.4013
	0.4197	0.3870	UC	0.4273	0.4046
U4	0.4235	0.3958		0.4311	0.4133
	0.4168	0.3927	***	U9 0.4094 0.4022 0.4065 0.4134 0.4167 0.4239 0.4124 0.4094 0.4124 0.4094 0.4167 0.4199 0.4124 0.4167 0.4239 0.4124 0.4167 0.4199 0.4124 0.4167 0.4239 0.4124 0.4167 0.4199	0.4099
	0.3969	0.3834		0.4022	0.3997
115	0.4035	0.3865		0.4094	0.4031
U5	0.4065	0.3948	UA 0.4065 0.4134 0.4167 0.4094 0.4134 0.4204 0.4239 0.4167 0.4204 0.4273 0.4311 0.4239 0.4022 0.4094 0.4124 0.4049 0.4199 0.4124 0.4167 0.4239 0.4239 0.4124 0.4167 0.4239 0.4274 0.4239 0.4239 0.4239	0.4114	
	0.3995	0.3916		0.4049	0.4078
	0.4035	0.3865		0.4094	0.4031
110	0.4102	0.3896		0.4167	0.4065
U6	0.4134	0.3981	UE	0.4199	0.4150
	0.4065	0.3948		0.4124	0.4114
	0.4102	0.3896		0.4167	0.4065
	0.4168	0.3927		0.4239	0.4099
U7	0.4204	0.4013	UF	0.4274	0.4185
	0.4134	0.3981		0.4199	0.4150
	0.4168	0.3927		0.4239	0.4099
1.0	0.4235	0.3958		0.4311	0.4133
U8	0.4273	0.4046	UG	0.4349	0.4221
	0.4204	0.4013		0.4274 0.4199 0.4239 0.4311	0.4185

Region	CIE x	CIE y	Region	CIE x	CIE y
		T rank	(4000 K)		
	0.3731	0.3667		0.3764	0.3815
	0.3788	0.3702	то.	0.3826	0.3854
T1	0.3807	0.3778	19	0.3845	0.3930
	0.3748	0.3741	TO TO O.3764 O.3826 O.3826 O.3826 O.3889 O.3845 O.3889 O.3845 O.3951 O.3975 O.4040 O.3975 O.4040 O.3975 O.3889 O.3975 O.4040 O.3975 O.4040 O.3975 O.3885 O.3889 O.3889 O.3889 O.3889 O.3889 O.3889 O.3951 O.3975 O.4013 O.4040 O.3975 O.4040 O.3975 O.3865 O.3797 O.3865 O.3797 O.3865 O.3797 O.3865 O.3932 O.3975	0.3781	0.3889
	0.3788	0.3702		0.3826	0.3854
TO	0.3845	0.3736	Τ.	0.3889	0.3892
T2	0.3867	0.3814	T IA	0.3910	0.3970
	0.3807	0.3778		0.3845	0.3930
	0.3845	0.3736		0.3889	0.3892
TO	0.3902	0.3771		0.3951	0.3931
Т3	0.3926	0.3851	IB	0.3975	0.4011
	0.3867	0.3814		0.3910	0.3970
	0.3902	0.3771		0.3951	0.3931
T4	0.3959	0.3805	TO.	0.4013	0.3969
T4	0.3986	0.3887	805 TC 0.4013 0.4040 851 0.3975 0.3781	0.4040	0.4051
	0.3926	0.3851		0.4011	
	0.3748	0.3741		0.3781	0.3889
TE	0.3807	0.3778	TD	0.3845	0.3930
T5	0.3826	0.3854	ID	0.3865	0.4006
	0.3764	0.3815		0.3975 0.3910 0.3951 0.4013 0.4040 0.3975 0.3781 0.3845 0.3865 0.3797 0.3845 0.3910 0.3932 0.3865	0.3963
	0.3807	0.3778		0.3845 0.3889 0.3951 0.3975 0.3910 0.3951 0.4013 0.4040 0.3975 0.3781 0.3845 0.3865 0.3797 0.3845 0.3910 0.3932 0.3865 0.3910 0.3975 0.4000 0.3932	0.3930
Te	0.3867	0.3814	TE	0.3910	0.3970
T6	0.3889	0.3892	15	0.3932	0.4048
	0.3826	0.3854		0.3865	0.4006
	0.3867	0.3814		0.3910	0.3970
Т7	0.3926	0.3851	TE	0.3975	0.4011
17	0.3951	0.3931	IF	0.4000	0.4091
	0.3889 0.3892		0.3932	0.4048	
	0.3926	0.3851		0.3975	0.4011
ТО	0.3986	0.3887	TO	0.4040	0.4051
Т8	0.4013	0.3969	IG	0.4067	0.4133
	0.3951	0.3931		0.4000	0.4091



Region	CIEx	CIE y	Region	CIE x	CIE y
	:	R rank	(5000 K)		
	0.3429	0.3459		0.3434	0.3586
D4	0.3465	0.3489	DO.	0.3474	0.3618
R1	0.3469	0.3553	n9	0.3478	0.3682
	0.3431	0.3523	0.3434 0.3474	0.3436	0.3650
	0.3465	0.3489		0.3474	0.3618
DO.	0.3502	0.3518	D.4	0.3514	0.3649
R2	0.3508	0.3584	HA	0.3519	0.3715
	0.3469	0.3553	0.3474 0.3514 0.3514 0.3519 0.3478 0.3514 0.3519 0.3478 0.3554 0.3554 0.3561 0.3519 0.3554 0.3561 0.3561 0.3594 0.3603 0.3478 0.3436 0.3438 0.3438 0.3438 0.3438	0.3682	
	0.3502	0.3518		0.3514	0.3649
	0.3538	0.3547		0.3554	0.3681
R3	0.3546	0.3614	RB	0.3561	0.3748
	0.3508	0.3584		0.3519	0.3715
	0.3538	0.3547		0.3554	0.3681
	0.3575	0.3576		0.3594	0.3713
R4	0.3584	0.3644	RC 0.3519 0.3554 0.3554 0.3594 0.3603 0.3561 0.3436 0.3478	0.3603	0.3781
	0.3546	0.3614		0.3748	
	0.3431	0.3523		0.3436	0.3650
	0.3469	0.3553		0.3478	0.3682
R5	0.3474	0.3618	RA 0.3514 0.3519 0.3478 0.3514 0.3554 0.3554 0.3561 0.3554 0.3554 0.3594 0.3603 0.3561 0.3436 0.3478 0.3482 0.3439 0.3478 0.3525 0.3482 0.3525 0.3482 0.3561 0.3569 0.3525	0.3482	0.3747
	0.3434	0.3586		0.3439	0.3713
	0.3469	0.3553		0.3478	0.3682
	0.3508	0.3584		0.3519	0.3715
R6	0.3514	0.3649	RE	0.3525	0.3781
	0.3474	0.3618		0.3482	0.3747
	0.3508	0.3584		0.3519	0.3715
_	0.3546	0.3614		0.3561	0.3748
R7	0.3554	0.3681	RF	0.3569	0.3815
	0.3514	0.3649		0.3525	0.3781
	0.3546	0.3614		0.3561	0.3748
_	0.3584	0.3644	_	0.3603	0.3781
R8	0.3594	0.3713	RG	0.3612	0.3849
	0.3554	0.3681		0.3569	0.3815

Region	CIE x	CIE y	Region	CIE x	CIE y
		Q rank	(5700 K)		
	0.3288	0.3342		0.3280	0.3452
01	0.3323	0.3372	00	0.3319	0.3485
Q1	0.3321	0.3429	- Q9	0.3316	0.3542
	0.3284	0.3397		0.3276	0.3507
	0.3323	0.3372		0.3319	0.3485
00	0.3358	0.3401	0.4	0.3357	0.3519
Q2	0.3358	0.3460	QA	0.3356	0.3578
	0.3321	0.3429		0.3316	0.3542
	0.3358	0.3401		0.3357	0.3519
00	0.3393	0.3430	OD	0.3395	0.3553
Q3	0.3394	0.3491	QB	0.3396	0.3614
	0.3358	0.3460	-	0.3356	0.3578
	0.3393	0.3430	QC 0.3434 0.3436 0.3436 0.3396	0.3395	0.3553
04	0.3429	0.3459		0.3434	0.3586
Q4	0.3431	0.3523		0.3436	0.3650
	0.3394	0.3491		0.3614	
	0.3284	0.3397		0.3276	0.3507
OF	0.3321	0.3429	OD	0.3316	0.3542
Q5	0.3319	0.3485	QD	0.3314	0.3599
	0.3280	0.3452		0.3357 0.3395 0.3396 0.3356 0.3395 0.3434 0.3436 0.3396 0.3276 0.3316	0.3561
	0.3321	0.3429	QD 0.33 QD 0.33 0.33 0.33 0.33 0.33	0.3316	0.3542
06	0.3358	0.3460	OF	0.3356	0.3578
Q6	0.3357	0.3519	QE	0.3356	0.3637
	0.3319	0.3485		0.3314	0.3599
	0.3358	0.3460		0.3356	0.3578
07	0.3394	0.3491	OF.	0.3396	0.3614
Q7	0.3395	0.3553	QF	0.3397	0.3675
	0.3357	0.3519		0.3356	0.3637
	0.3394	0.3491		0.3396	0.3614
00	0.3431	0.3523	00	0.3436	0.3650
Q8	0.3434 0.3586 QG 0.343	0.3439	0.3713		
	0.3395	0.3553		0.3397	0.3675



Region	CIEx	CIE y	Region	CIEx	CIE y
		P rank	(6500 K)		
	0.3133	0.3218		0.3113	0.3314
D4	0.3171	0.3255	DO	0.3154	0.3354
P1	0.3163	0.3305	P9	0.3146	0.3404
	0.3123	0.3266	92 PA 0.3154 92 PA 0.3154 92 PA 0.3196 43 0.3189 05 0.3146 92 0.3196 29 PB 0.3237 82 0.3232 43 0.3189 29 0.3237 66 PC 0.3275 82 0.3275 82 0.3275 82 0.3232 66 0.3103 05 PD 0.3146 054 0.3138 14 0.3093 05 0.3146 43 PE 0.3189 95 0.3189 95 0.3189 82 PF	0.3361	
	0.3171	0.3255		0.3154	0.3354
500	0.3210	0.3292		0.3196	0.3395
P2	0.3203	0.3343	PA	0.3189	0.3446
	0.3163	0.3305	•	0.3146	0.3404
	0.3210	0.3292		0.3196	0.3395
500	0.3248	0.3329		0.3237	0.3435
P3	0.3242	0.3382	PB	0.3232	0.3489
	0.3203	0.3343	•	0.3189	0.3446
	0.3248	0.3329	3366 PC 0.3279 0.3275 3382 0.3232	0.3237	0.3435
54	0.3286	0.3366		0.3279	0.3476
P4	0.3282	0.3421		0.3275	0.3531
	0.3242	0.3382		0.3489	
	0.3123	0.3266		0.3103	0.3361
5.5	0.3163	0.3305		0.3146	0.3404
P5	0.3154	0.3354	PD	0.3138	0.3453
	0.3113	0.3314	PD (0.3093	0.3409
	0.3163	0.3305		0.3146	0.3404
-	0.3203	0.3343		0.3189	0.3446
P6	0.3196	0.3395	PE	0.3182	0.3498
	0.3154	0.3354	***	0.3138	0.3453
	0.3203	0.3343		0.3189	0.3446
57	0.3242	0.3382	D.F.	0.3232	0.3489
P7	0.3237	0.3435	PF	0.3227	0.3542
	0.3196	0.3395		0.3182	0.3498
	0.3242	0.3382		0.3232	0.3489
	0.3282	0.3421		0.3275	0.3531
P8	0.3279	0.3476	PG	0.3271	0.3586
	0.3237	0.3435		0.3227	0.3542

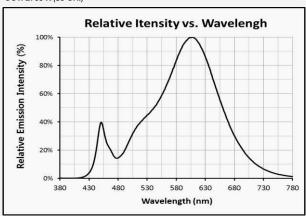
Note: Samsung maintains measurement tolerance of: Cx, $Cy = \pm 0.005$



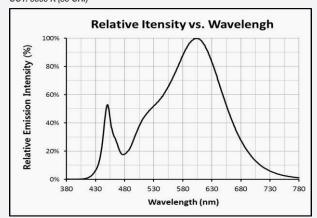
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 60$ mA, $T_s = 25$ °C)

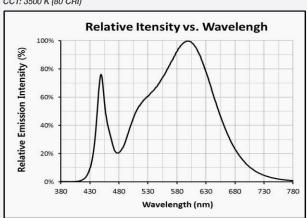
CCT: 2700 K (80 CRI)



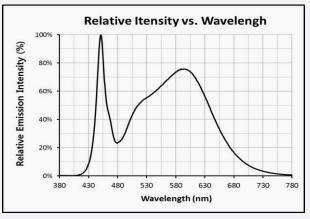
CCT: 3000 K (80 CRI)



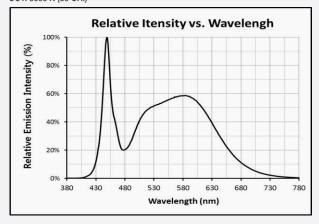
CCT: 3500 K (80 CRI)



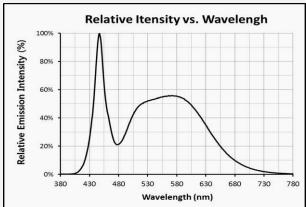
CCT: 4000 K (80 CRI)



CCT: 5000 K (80 CRI)

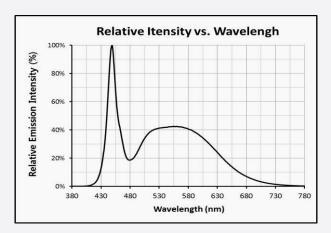


CCT: 5700 K (80 CRI)

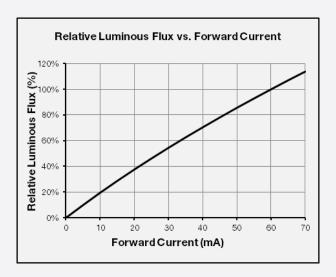


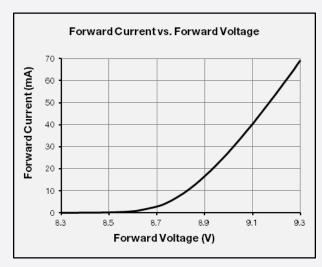


CCT: 6500 K (80 CRI)

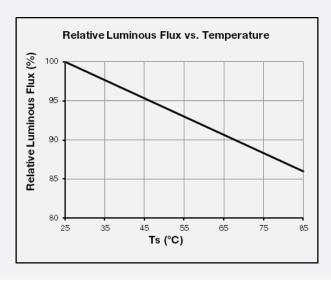


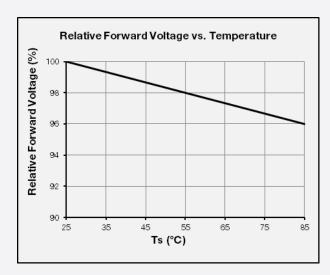
b) Forward Current Characteristics (T_s = 25 °C)





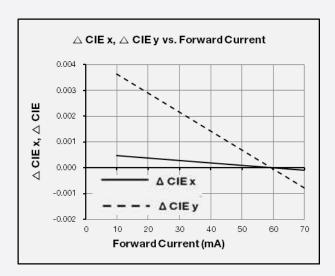
c) Temperature Characteristics (I_F = 60 mA)

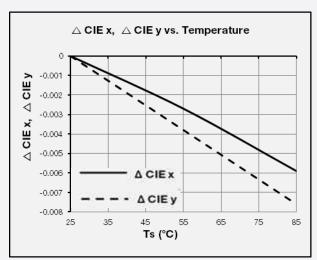




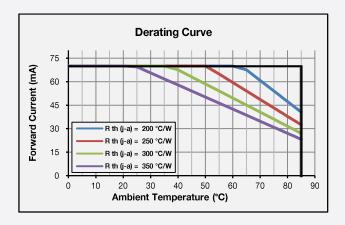


d) Color Shift Characteristics (I_F = 60 mA, T_s = 25 °C)

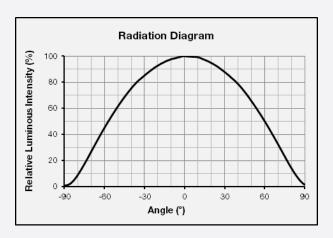




e) Derating Curve

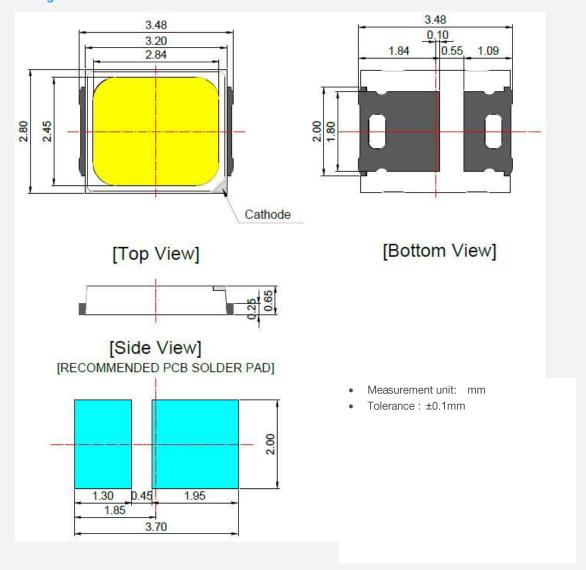


f) Beam Angle Characteristics ($I_F = 60$ mA, $T_s = 25$ °C)





4. Outline Drawing & Dimension



Notes:

- 1) T_s point and measurement method:
 - 1 Measure one point at the cathode pad, if necessary remove PSR of PCB to reach Ts point.
 - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.



5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
Room Temperature Life Test	25 °C, DC 70 mA	1000 h	22
High Temperature Life Test	85 °C, DC 70 mA	1000 h	22
High Temperature Humidity Life Test	60 °C, 90 % RH, DC 70 mA	1000 h	22
Low Temperature Life Test	-40 °C, DC 70 mA	1000 h	22
Powered Temperature Cycle Test	-45 °C ~ 85 °C, each 20 min, on/off 5 min Temp. Change time 100min, DC 70 mA	100 cycles	22
Temperature Cycling	-45 °C / 15 min ↔ 125 °C / 15 min	200 cycles	100
High Temperature Storage	85 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	R₁: 10 MΩ R₂: 1.5 kΩ C: 100 pF V: ±2 kV	5 times	30

b) Criteria for Judging the Damage

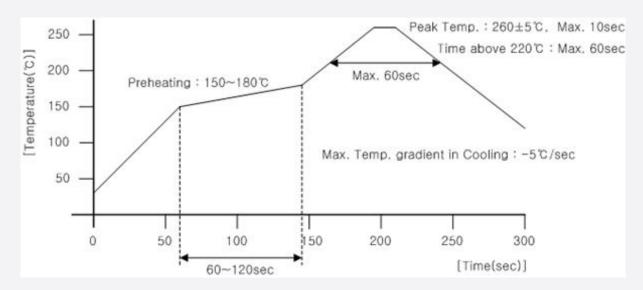
Itom	Complete	Test Condition	Limit		
ltem	Symbol	(T _s = 25 °C)	Min	Max	
Forward Voltage	V _F	$I_F = 60 \text{ mA}$	Init. Value * 0.9	Init. Value * 1.1	
Luminous Flux	Ф	I _F = 60 mA	Init. Value * 0.7	Init. Value * 1.1	



6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



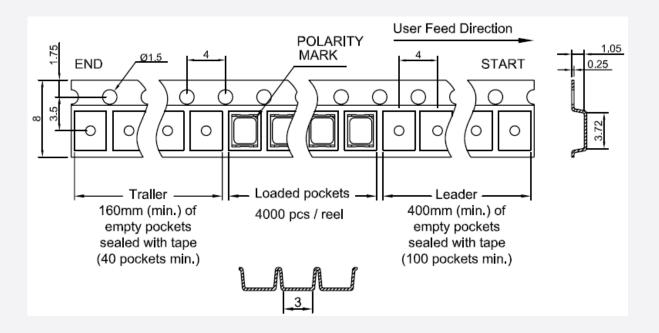
b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.



7. Tape & Reel

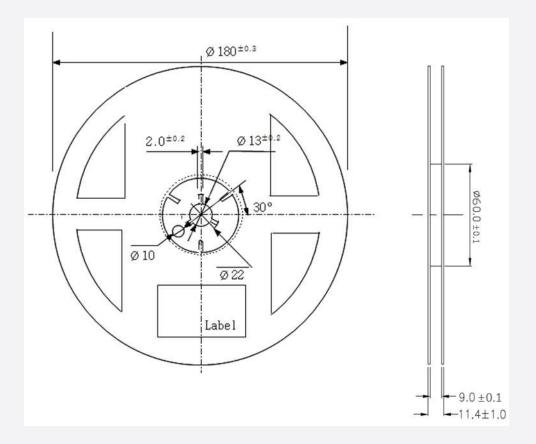
a) Taping Dimension





b) Reel Dimension (max 4,000 pcs)

(unit: mm)



Notes:

1) Quantity: The quantity/reel is 4,000 pcs

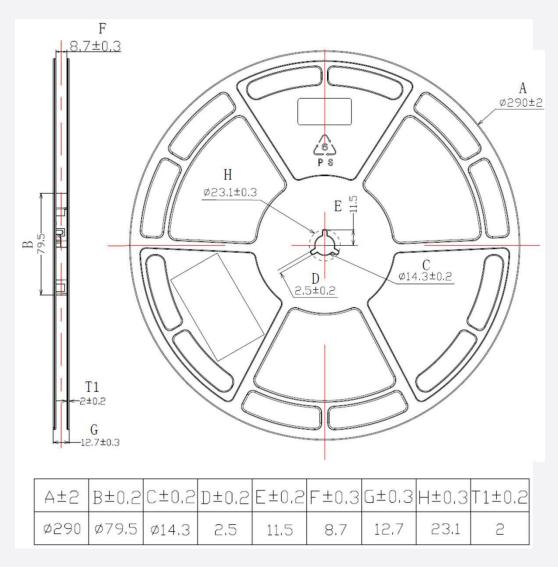
2) All dimensions are millimeters (tolerance: ±0.2mm)

3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag



c) Reel Dimension (max 12,000 pcs)

(unit: mm)



Notes:

1) Quantity: The quantity/reel is 12,000 pcs

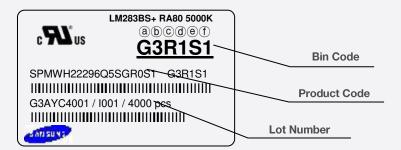
2) All dimensions are millimeters (tolerance: ±0.2mm)

3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag



8. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 6)

Bin Code:

(a) (b): Forward Voltage bin (refer to page 10)(c) (c) (c) (c) (c) (d): Chromaticity bin (refer to page 11-18)(e) (f): Luminous Flux bin (refer to page 7)

b) Lot Number

The lot number is composed of the following characters:



123456789 / labc / 4,000 pcs

① : Production site (S: Giheung, Korea, G: Tianjin, China)

② : 3 (LED)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

(Z: 2015, A: 2016, B: 2017...)

(1~9, A, B, C)

6 : Day (1~9, A, B~V)

789 abc : Product serial number

